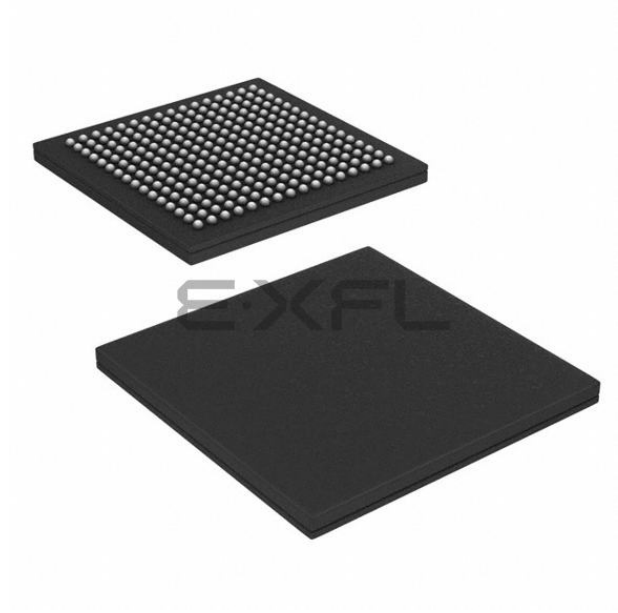


Welcome to E-XFL.COM

Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In-System Reprogrammable™ (ISR™) CMOS
Delay Time tpd(1) Max	20 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	256
Number of Gates	-
Number of I/O	197
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy37256vp256-66bbc

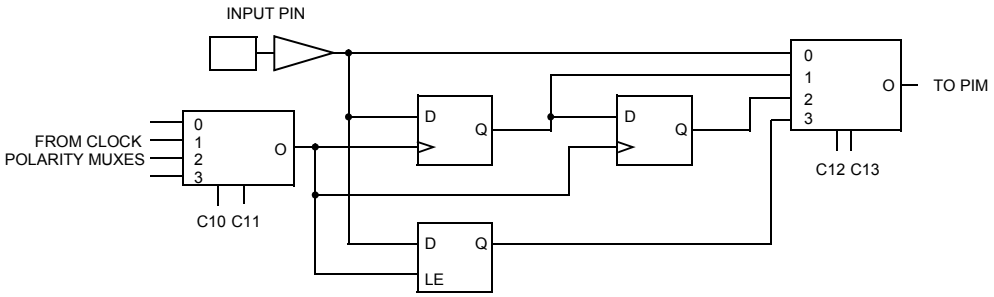


Figure 3. Input Macrocell

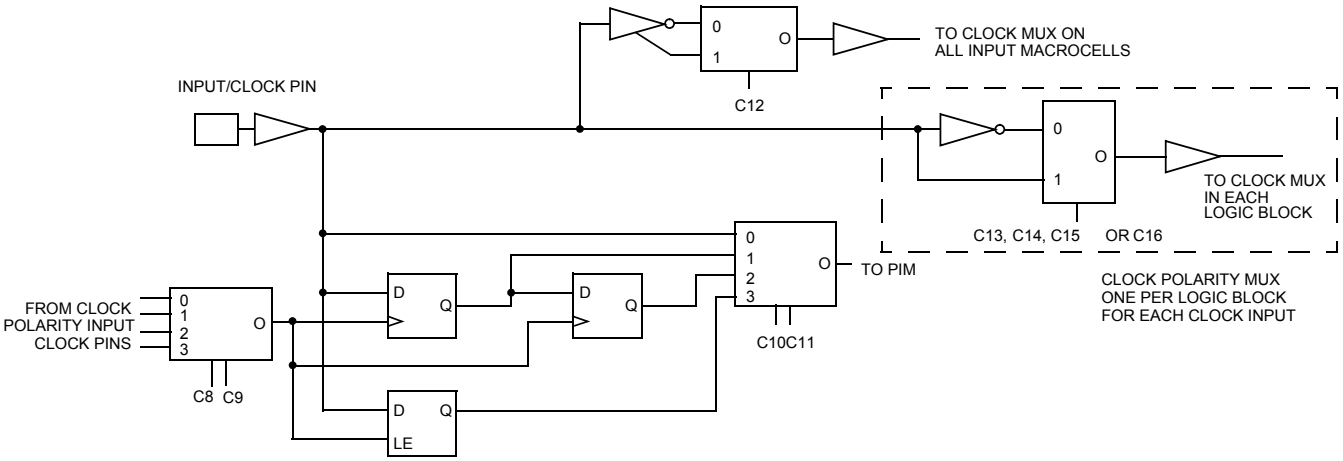


Figure 4. Input/Clock Macrocell

Clocking

Each I/O and buried macrocell has access to four synchronous clocks (CLK0, CLK1, CLK2 and CLK3) as well as an asynchronous product term clock PTCLK. Each input macrocell has access to all four synchronous clocks.

Dedicated Inputs/Clocks

Five pins on each member of the Ultra37000 family are designated as input-only. There are two types of dedicated inputs on Ultra37000 devices: input pins and input/clock pins. *Figure 3* illustrates the architecture for input pins. Four input options are available for the user: combinatorial, registered, double-registered, or latched. If a registered or latched option is selected, any one of the input clocks can be selected for control.

Figure 4 illustrates the architecture for the input/clock pins. Like the input pins, input/clock pins can be combinatorial, registered, double-registered, or latched. In addition, these pins feed the clocking structures throughout the device. The clock path at the input has user-configurable polarity.

Product Term Clocking

In addition to the four synchronous clocks, the Ultra37000 family also has a product term clock for asynchronous clocking. Each logic block has an independent product term clock which is available to all 16 macrocells. Each product term clock also supports user configurable polarity selection.

Timing Model

One of the most important features of the Ultra37000 family is the simplicity of its timing. All delays are worst case and system performance is unaffected by the features used. *Figure 5* illustrates the true timing model for the 167-MHz devices in high speed mode. For combinatorial paths, any input to any output incurs a 6.5-ns worst-case delay regardless of the amount of logic used. For synchronous systems, the input set-up time to the output macrocells for any input is 3.5 ns and the clock to output time is also 4.0 ns. These measurements are for any output and synchronous clock, regardless of the logic used.

The Ultra37000 features:

- No fanout delays
- No expander delays
- No dedicated vs. I/O pin delays
- No additional delay through PIM
- No penalty for using 0–16 product terms
- No added delay for steering product terms
- No added delay for sharing product terms
- No routing delays
- No output bypass delays

The simple timing model of the Ultra37000 family eliminates unexpected performance penalties.

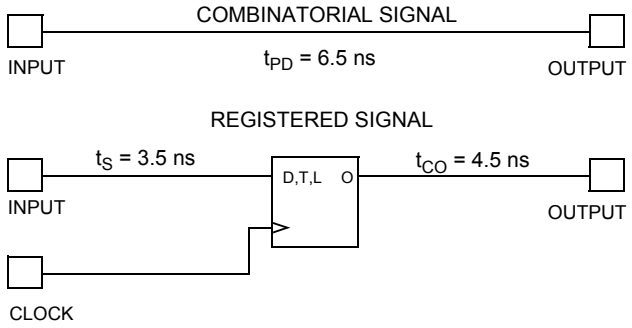


Figure 5. Timing Model for CY37128

JTAG and PCI Standards

PCI Compliance

5V operation of the Ultra37000 is fully compliant with the PCI Local Bus Specification published by the PCI Special Interest Group. The 3.3V products meet all PCI requirements except for the output 3.3V clamp, which is in direct conflict with 5V tolerance. The Ultra37000 family's simple and predictable timing model ensures compliance with the PCI AC specifications independent of the design.

IEEE 1149.1-compliant JTAG

The Ultra37000 family has an IEEE 1149.1 JTAG interface for both Boundary Scan and ISR.

Boundary Scan

The Ultra37000 family supports Bypass, Sample/Preload, Extest, Idcode, and Usercode boundary scan instructions. The JTAG interface is shown in *Figure 6*.

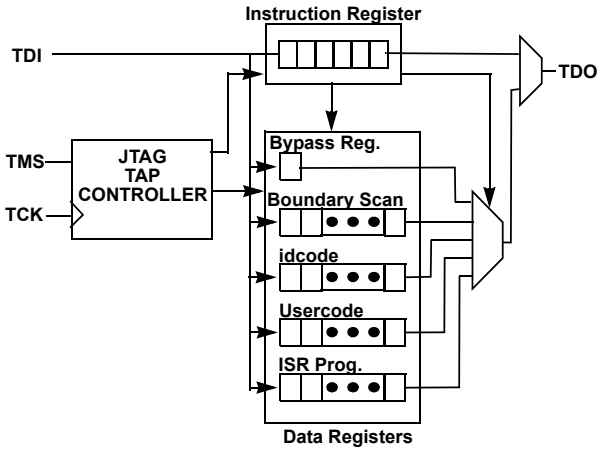


Figure 6. JTAG Interface

In-System Reprogramming (ISR)

In-System Reprogramming is the combination of the capability to program or reprogram a device on-board, and the ability to support design changes without changing the system timing or device pinout. This combination means design changes during debug or field upgrades do not cause board respins. The Ultra37000 family implements ISR by providing a JTAG compliant interface for on-board programming, robust routing resources for pinout flexibility, and a simple timing model for consistent system performance.

Development Software Support

Warp

Warp is a state-of-the-art compiler and complete CPLD design tool. For design entry, Warp provides an IEEE-STD-1076/1164 VHDL text editor, an IEEE-STD-1364 Verilog text editor, and a graphical finite state machine editor. It provides optimized synthesis and fitting by replacing basic circuits with ones pre-optimized for the target device, by implementing logic in unused memory and by perfect communication between fitting and synthesis. To facilitate design and debugging, Warp provides graphical timing simulation and analysis.

Warp Professional™

Warp Professional contains several additional features. It provides an extra method of design entry with its graphical block diagram editor. It allows up to 5 ms timing simulation instead of only 2 ms. It allows comparison of waveforms before and after design changes.

Warp Enterprise™

Warp Enterprise provides even more features. It provides unlimited timing simulation and source-level behavioral simulation as well as a debugger. It has the ability to generate graphical HDL blocks from HDL text. It can even generate testbenches.

Warp is available for PC and UNIX platforms. Some features are not available in the UNIX version. For further information see the *Warp* for PC*, Warp* for UNIX, *Warp* Professional and *Warp* Enterprise data sheets on Cypress's web site (www.cypress.com).

Third-Party Software

Although *Warp* is a complete CPLD development tool on its own, it interfaces with nearly every third party EDA tool. All major third-party software vendors provide support for the Ultra37000 family of devices. Refer to the third-party software data sheet or contact your local sales office for a list of currently supported third-party vendors.

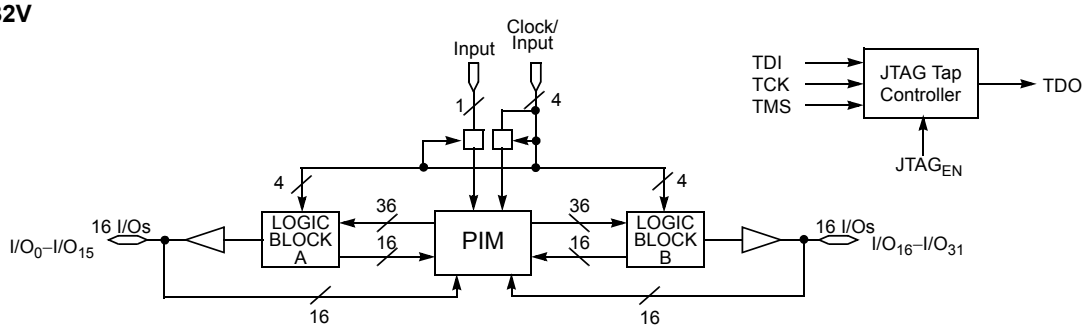
Programming

There are four programming options available for Ultra37000 devices. The first method is to use a PC with the 37000 UltraISR programming cable and software. With this method, the ISR pins of the Ultra37000 devices are routed to a connector at the edge of the printed circuit board. The 37000 UltraISR programming cable is then connected between the parallel port of the PC and this connector. A simple configuration file instructs the ISR software of the programming operations to be performed on each of the Ultra37000 devices in the system. The ISR software then automatically completes all of the necessary data manipulations required to accomplish the programming, reading, verifying, and other ISR functions. For more information on the Cypress ISR Interface, see the ISR Programming Kit data sheet (CY3700i).

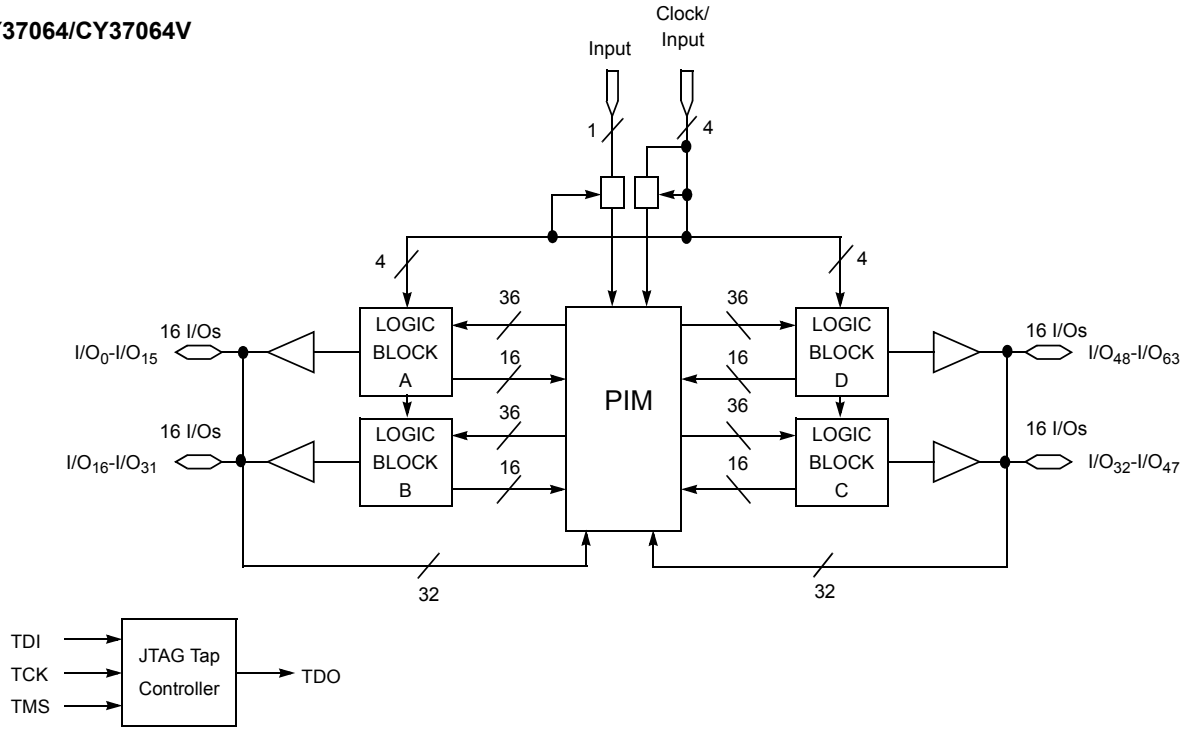
The second method for programming Ultra37000 devices is on automatic test equipment (ATE). This is accomplished through a file created by the ISR software. Check the Cypress website for the latest ISR software download information.

Logic Block Diagrams

CY37032/CY37032V

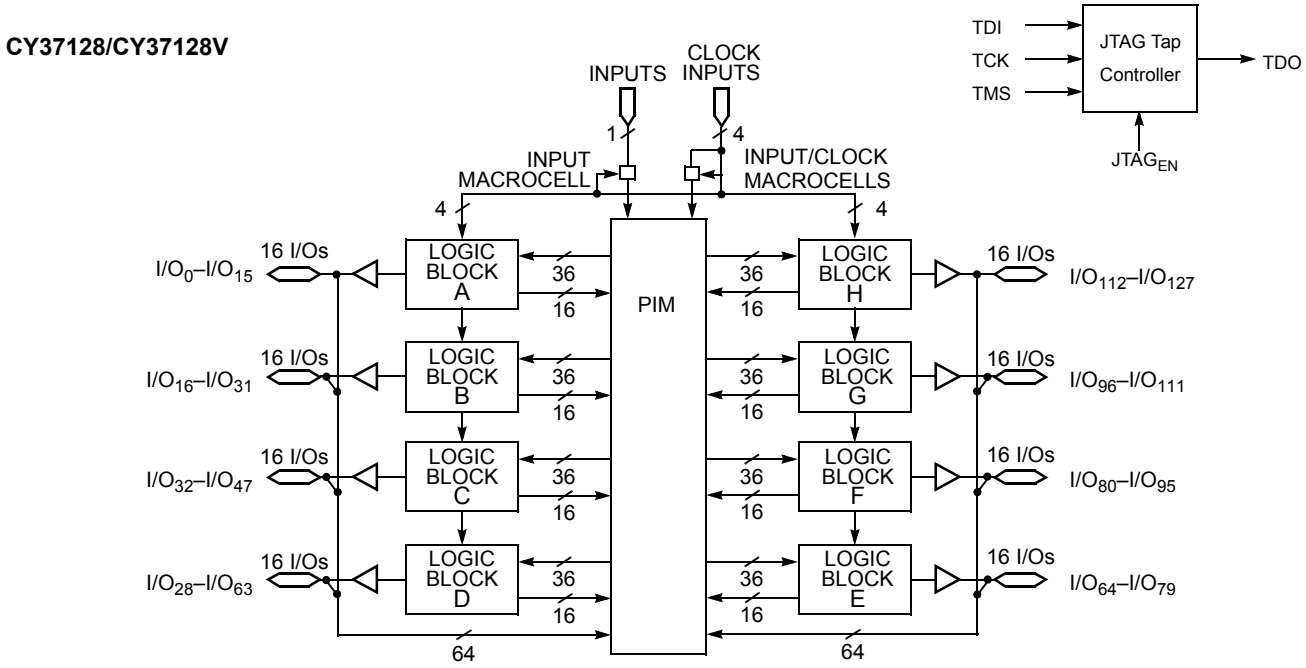


CY37064/CY37064V

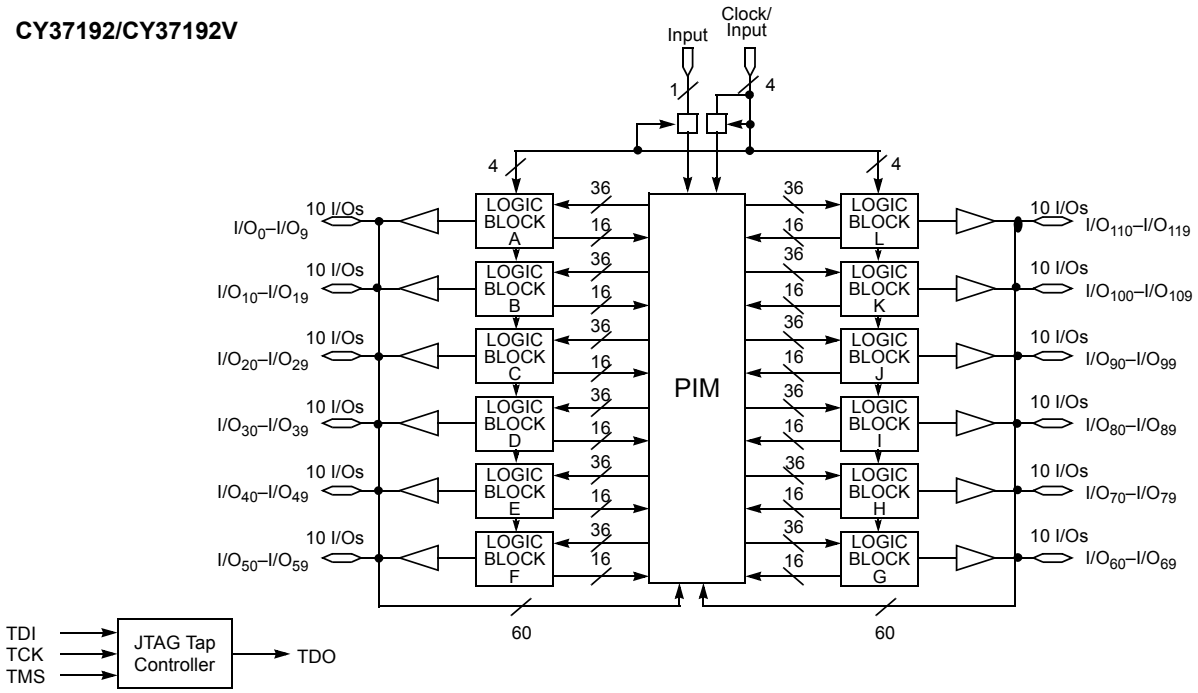


Logic Block Diagrams (continued)

CY37128/CY37128V

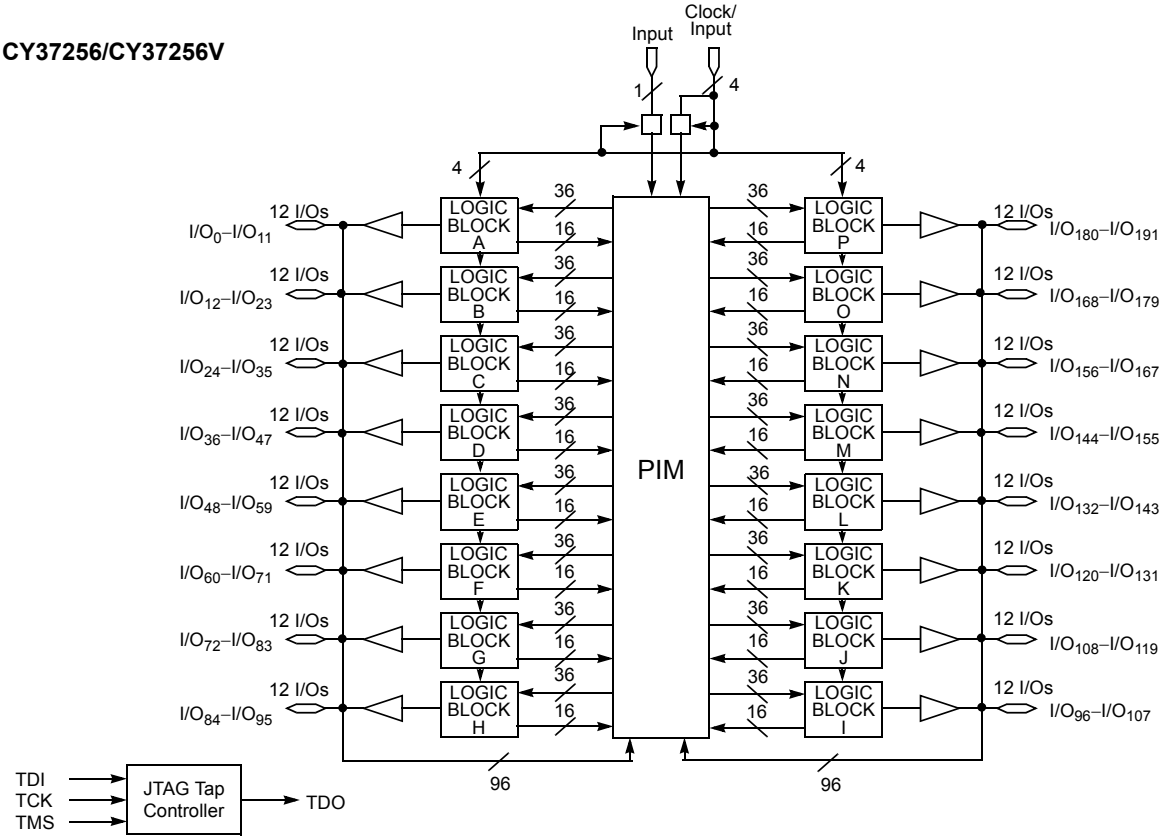


CY37192/CY37192V



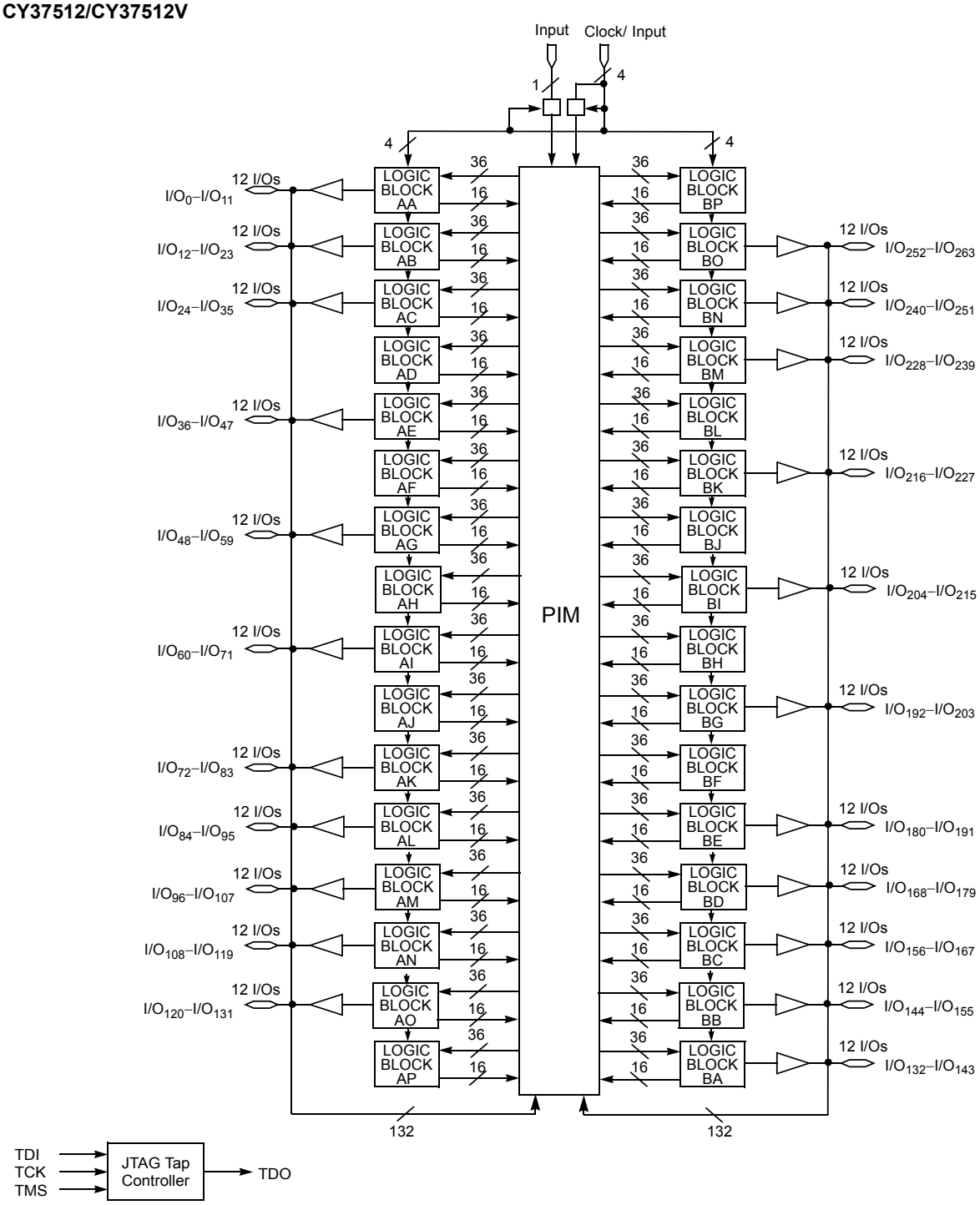
Logic Block Diagrams (continued)

CY37256/CY37256V



Logic Block Diagrams (continued)

CY37512/CY37512V



5.0V Device Characteristics Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... –65°C to +150°C

Ambient Temperature with Power Applied..... –55°C to +125°C

Supply Voltage to Ground Potential ..... –0.5V to +7.0V

DC Voltage Applied to Outputs in High-Z State..... –0.5V to +7.0V

DC Input Voltage ..... –0.5V to +7.0V

DC Program Voltage..... 4.5 to 5.5V

Current into Outputs ..... 16 mA

Static Discharge Voltage..... > 2001V (per MIL-STD-883, Method 3015)

Latch-up Current..... > 200 mA

Operating Range[2]

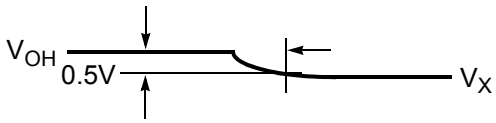
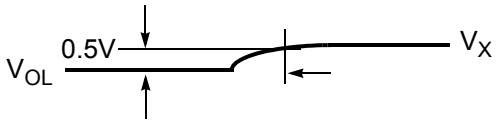
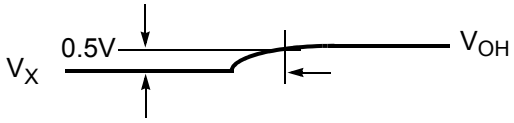
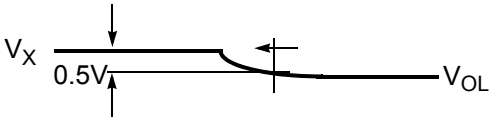
Range	Ambient Temperature[2]	Junction Temperature	Output Condition	V_{CC}	V_{CCO}
Commercial	0°C to +70°C	0°C to +90°C	5V	5V ± 0.25V	5V ± 0.25V
			3.3V	5V ± 0.25V	3.3V ± 0.3V
Industrial	–40°C to +85°C	–40°C to +105°C	5V	5V ± 0.5V	5V ± 0.5V
			3.3V	5V ± 0.5V	3.3V ± 0.3V
Military[3]	–55°C to +125°C	–55°C to +130°C	5V	5V ± 0.5V	5V ± 0.5V
			3.3V	5V ± 0.5V	3.3V ± 0.3V

5.0V Device Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions		Min.	Typ.	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC} = Min.	I_{OH} = –3.2 mA (Com'l/Ind)[4]	2.4			V
			I_{OH} = –2.0 mA (Mil)[4]	2.4			V
V_{OHZ}	Output HIGH Voltage with Output Disabled[5]	V_{CC} = Max.	I_{OH} = 0 µA (Com'l)[6]			4.2	V
			I_{OH} = 0 µA (Ind/Mil)[6]			4.5	V
			I_{OH} = –100 µA (Com'l)[6]			3.6	V
			I_{OH} = –150 µA (Ind/Mil)[6]			3.6	V
V_{OL}	Output LOW Voltage	V_{CC} = Min.	I_{OL} = 16 mA (Com'l/Ind)[4]			0.5	V
			I_{OL} = 12 mA (Mil)[4]			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs[7]		2.0		V_{CCmax}	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs[7]		–0.5		0.8	V
I_{IX}	Input Load Current	V_I = GND OR V_{CC}, Bus-Hold Disabled		–10		10	µA
I_{OZ}	Output Leakage Current	V_O = GND or V_{CC}, Output Disabled, Bus-Hold Disabled		–50		50	µA
I_{OS}	Output Short Circuit Current[5, 8]	V_{CC} = Max., V_{OUT} = 0.5V		–30		–160	mA
I_{BHL}	Input Bus-Hold LOW Sustaining Current	V_{CC} = Min., V_{IL} = 0.8V		+75			µA
I_{BHH}	Input Bus-Hold HIGH Sustaining Current	V_{CC} = Min., V_{IH} = 2.0V		–75			µA
I_{BHLO}	Input Bus-Hold LOW Overdrive Current	V_{CC} = Max.				+500	µA
I_{BHHO}	Input Bus-Hold HIGH Overdrive Current	V_{CC} = Max.				–500	µA

Notes:

2. Normal Programming Conditions apply across Ambient Temperature Range for specified programming methods. For more information on programming the Ultra37000 Family devices, please refer to the Application Note titled "An Introduction to In System Reprogramming with the Ultra37000."
3. T_A is the "Instant On" case temperature.
4. I_{OH} = –2 mA, I_{OL} = 2 mA for TDO.
5. Tested initially and after any design or process changes that may affect these parameters.
6. When the I/O is output disabled, the bus-hold circuit can weakly pull the I/O to above 3.6V if no leakage current is allowed. Note that all I/Os are output disabled during ISR programming. Refer to the application note "Understanding Bus-Hold" for additional information.
7. These are absolute values with respect to device ground. All overshoots due to system or tester noise are included.
8. Not more than one output should be tested at a time. Duration of the short circuit should not exceed 1 second. V_{OUT} = 0.5V has been chosen to avoid test problems caused by tester ground degradation.

Parameter[11]	V_X	Output Waveform—Measurement Level
$t_{ER(-)}$	1.5V	
$t_{ER(+)}$	2.6V	
$t_{EA(+)}$	1.5V	
$t_{EA(-)}$	V_{the}	

(d) Test Waveforms

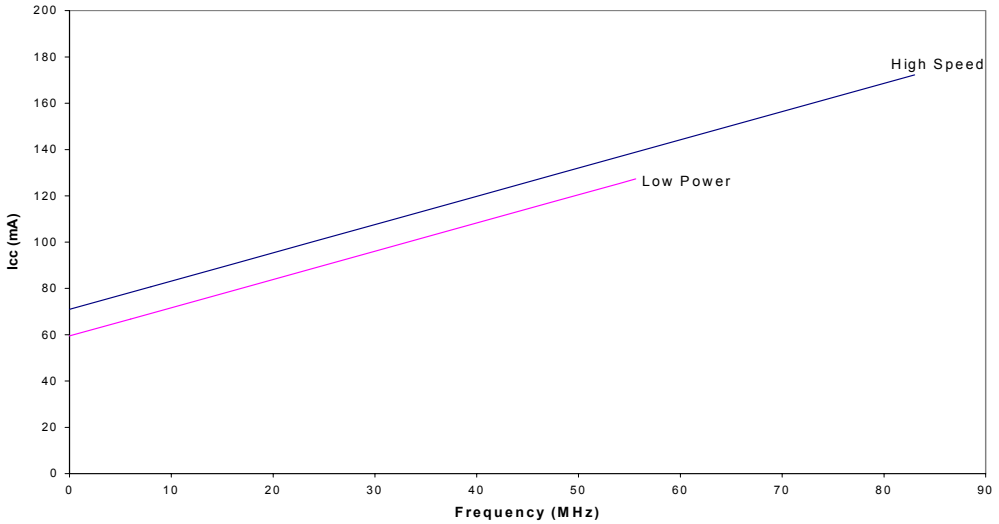
Switching Characteristics Over the Operating Range [12]

Parameter	Description	Unit
Combinatorial Mode Parameters		
t_{PD}[13, 14, 15]	Input to Combinatorial Output	ns
t_{PDL}[13, 14, 15]	Input to Output Through Transparent Input or Output Latch	ns
t_{PDLL}[13, 14, 15]	Input to Output Through Transparent Input and Output Latches	ns
t_{EA}[13, 14, 15]	Input to Output Enable	ns
t_{ER}[11, 13]	Input to Output Disable	ns
Input Register Parameters		
t_{WL}	Clock or Latch Enable Input LOW Time[8]	ns
t_{WH}	Clock or Latch Enable Input HIGH Time[8]	ns
t_{IS}	Input Register or Latch Set-up Time	ns
t_{IH}	Input Register or Latch Hold Time	ns
t_{ICO}[13, 14, 15]	Input Register Clock or Latch Enable to Combinatorial Output	ns
t_{ICOL}[13, 14, 15]	Input Register Clock or Latch Enable to Output Through Transparent Output Latch	ns
Synchronous Clocking Parameters		
t_{CO}[14, 15]	Synchronous Clock (CLK_0, CLK_1, CLK_2, or CLK_3) or Latch Enable to Output	ns
t_S[13]	Set-Up Time from Input to Sync. Clk (CLK_0, CLK_1, CLK_2, or CLK_3) or Latch Enable	ns
t_H	Register or Latch Data Hold Time	ns
t_{CO2}[13, 14, 15]	Output Synchronous Clock (CLK_0, CLK_1, CLK_2, or CLK_3) or Latch Enable to Combinatorial Output Delay (Through Logic Array)	ns
t_{SCS}[13]	Output Synchronous Clock (CLK_0, CLK_1, CLK_2, or CLK_3) or Latch Enable to Output Synchronous Clock (CLK_0, CLK_1, CLK_2, or CLK_3) or Latch Enable (Through Logic Array)	ns
t_{SL}[13]	Set-Up Time from Input Through Transparent Latch to Output Register Synchronous Clock (CLK_0 CLK_1, CLK_2, or CLK_3) or Latch Enable	ns
t_{HL}	Hold Time for Input Through Transparent Latch from Output Register Synchronous Clock (CLK_0, CLK_1, CLK_2, or CLK_3) or Latch Enable	ns

Notes:
11. t_{ER} measured with 5-pF AC Test Load and t_{EA} measured with 35-pF AC Test Load.
12. All AC parameters are measured with two outputs switching and 35-pF AC Test Load.
13. Logic Blocks operating in Low-Power Mode, add t_{LP} to this spec.
14. Outputs using Slow Output Slew Rate, add t_{SLEW} to this spec.
15. When V_{CCO} = 3.3V, add $t_{3.3IO}$ to this spec.

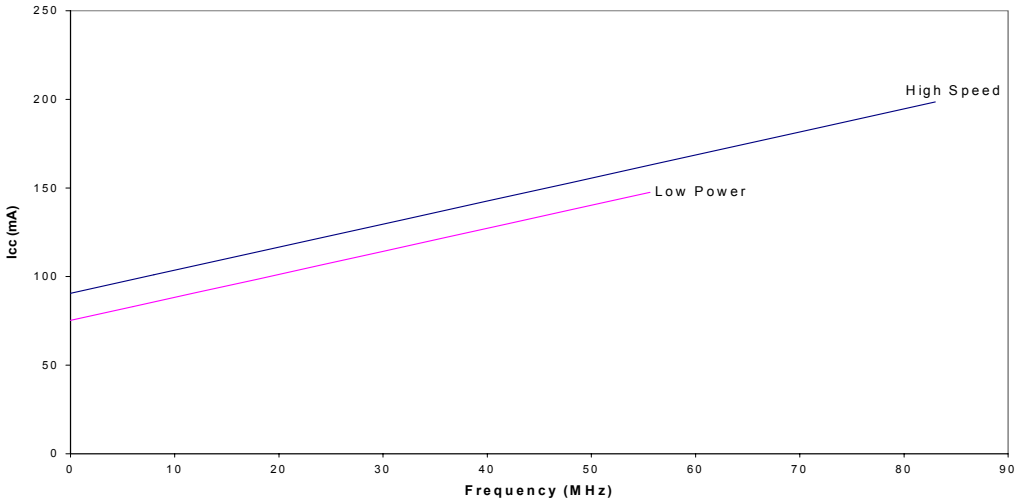
Typical 3.3V Power Consumption (continued)

CY37384V



The typical pattern is a 16-bit up counter, per logic block, with outputs disabled.
V_{CC} = 3.3V, T_A = Room Temperature

CY37512V



The typical pattern is a 16-bit up counter, per logic block, with outputs disabled.
V_{CC} = 3.3V, T_A = Room Temperature

Pin Configurations[20] (continued)

100-ball Fine-Pitch BGA (BB100) for CY37064V
Top View

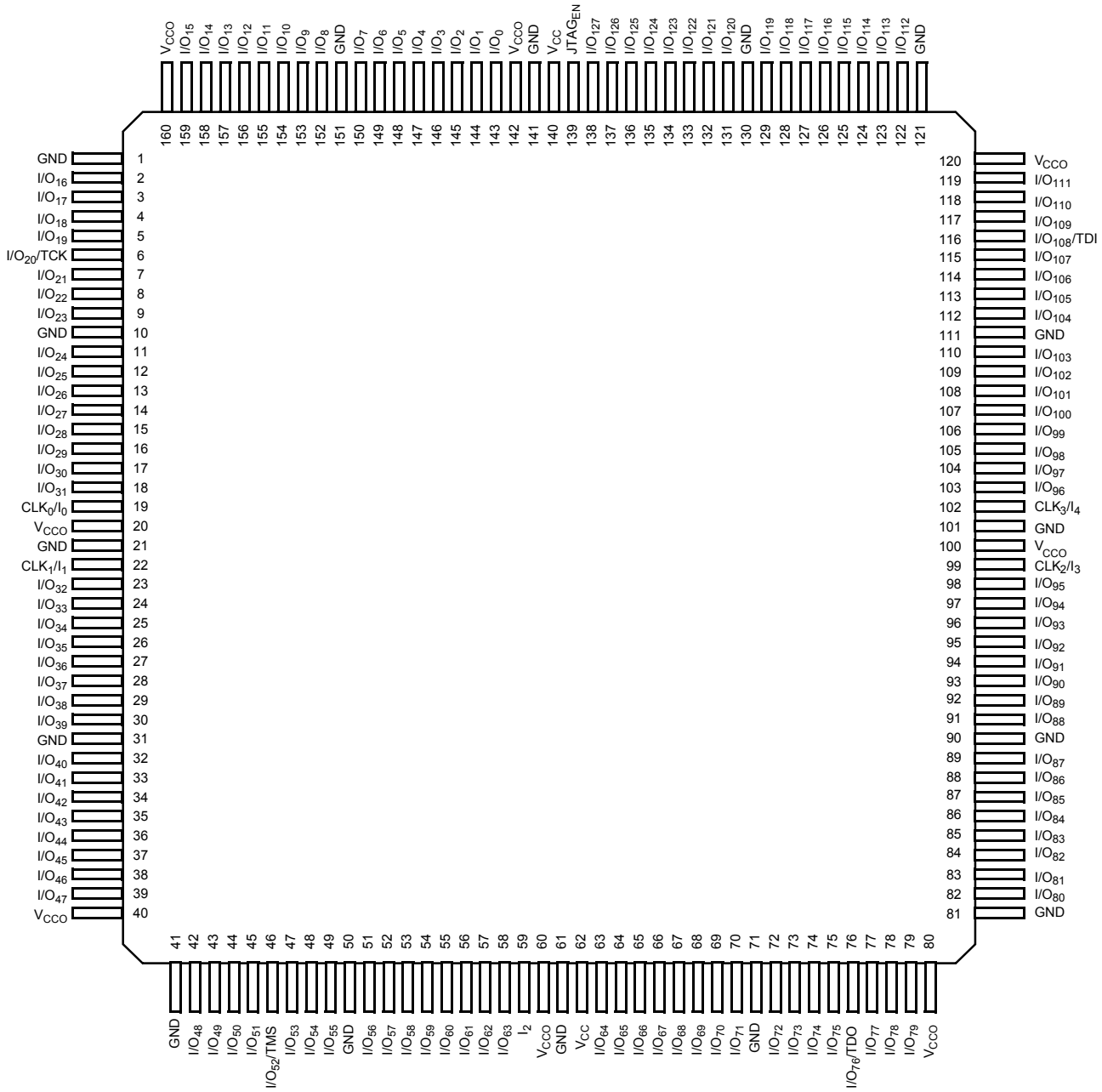
	1	2	3	4	5	6	7	8	9	10
A	NC	NC	I/O_7	I/O_5	I/O_2	I/O_{62}	I/O_{60}	I/O_{58}	I/O_{57}	I/O_{56}
B	I/O_9	I/O_8	I/O_6	I/O_4	I/O_1	I/O_{63}	V_{CC}	I/O_{59}	I/O_{55}	NC
C	I/O_{10}	TCK	V_{CC}	I/O_3	NC	NC	I/O_{61}	V_{CC}	TDI	I/O_{54}
D	I/O_{11}	NC	I/O_{12}	I/O_{13}	I/O_0	NC	I/O_{51}	I/O_{52}	CLK_3/I_4	I/O_{53}
E	I/O_{14}	CLK_0/I_0	I/O_{15}	NC	GND	GND	I/O_{48}	I/O_{49}	CLK_2/I_3	I/O_{50}
F	I/O_{17}	NC	NC	I/O_{16}	GND	GND	NC	NC	I_2	I/O_{47}
G	I/O_{22}	CLK_1/I_1	I/O_{21}	I/O_{19}	I/O_{18}	I/O_{46}	I/O_{45}	I/O_{44}	NC	I/O_{43}
H	I/O_{23}	TMS	V_{CC}	I/O_{20}	NC	I/O_{32}	I/O_{42}	V_{CC}	TDO	I/O_{41}
J	NC	I/O_{26}	I/O_{28}	NC	I/O_{31}	I/O_{33}	I/O_{35}	I/O_{37}	I/O_{39}	I/O_{40}
K	I/O_{24}	I/O_{25}	I/O_{27}	I/O_{29}	I/O_{30}	I/O_{34}	I/O_{36}	I/O_{38}	NC	NC

100-ball Fine-Pitch BGA (BB100) for CY37128V
Top View

	1	2	3	4	5	6	7	8	9	10
A	NC	I/O_9	I/O_8	I/O_6	I/O_3	I/O_{76}	I/O_{74}	I/O_{72}	I/O_{71}	I/O_{70}
B	I/O_{11}	I/O_{10}	I/O_7	I/O_5	I/O_2	I/O_{77}	V_{CC}	I/O_{73}	I/O_{68}	I/O_{69}
C	I/O_{12}	I/O_{13} TCK	V_{CC}	I/O_4	I/O_1	I/O_{78}	I/O_{75}	V_{CC}	I/O_{67} TDI	I/O_{66}
D	I/O_{14}	NC	I/O_{15}	I/O_{16}	I/O_0	I/O_{79}	I/O_{63}	I/O_{64}	CLK_3/I_4	I/O_{65}
E	I/O_{17}	CLK_0/I_0	I/O_{18}	I/O_{19}	GND	GND	I/O_{60}	I/O_{61}	CLK_2/I_3	I/O_{62}
F	I/O_{22}	JTAG EN	I/O_{21}	I/O_{20}	GND	GND	I/O_{59}	I/O_{58}	I_2	I/O_{57}
G	I/O_{27}	CLK_1/I_1	I/O_{26}	I/O_{24}	I/O_{23}	I/O_{56}	I/O_{55}	I/O_{54}	NC	I/O_{53}
H	I/O_{28}	I/O_{33} TMS	V_{CC}	I/O_{25}	I/O_{39}	I/O_{40}	I/O_{52}	V_{CC}	I/O_{47} TDO	I/O_{51}
J	I/O_{29}	I/O_{32}	I/O_{35}	V_{CC}	I/O_{38}	I/O_{41}	I/O_{43}	I/O_{45}	I/O_{48}	I/O_{50}
K	I/O_{30}	I/O_{31}	I/O_{34}	I/O_{36}	I/O_{37}	I/O_{42}	I/O_{44}	I/O_{46}	I/O_{49}	NC

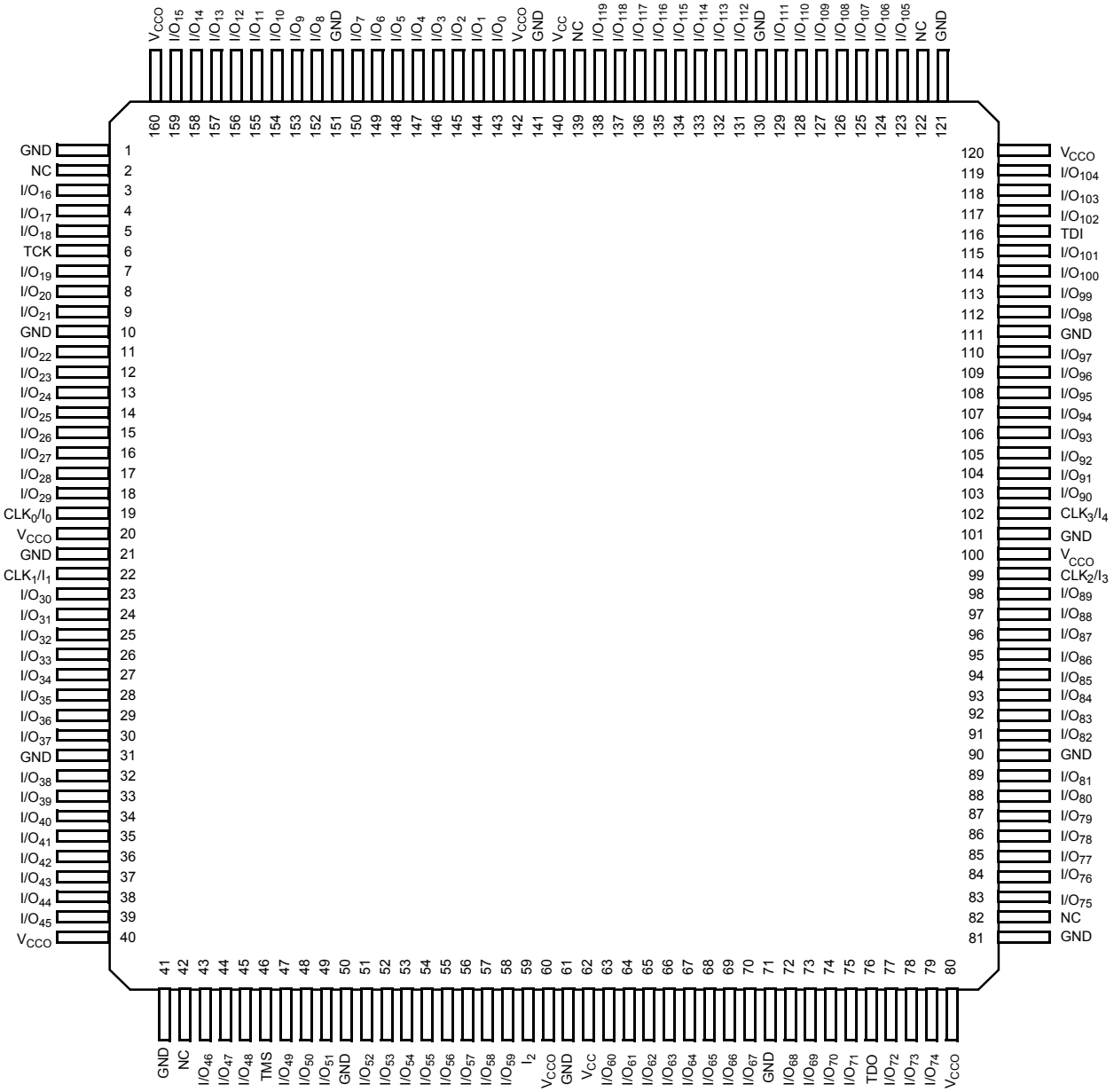
Pin Configurations[20] (continued)

160-Lead TQFP (A160) / CQFP (U162)
for CY37128(V) and CY37256(V)
Top View



Pin Configurations[20] (continued)

160-Lead TQFP (A160) for CY37192(V)
Top View

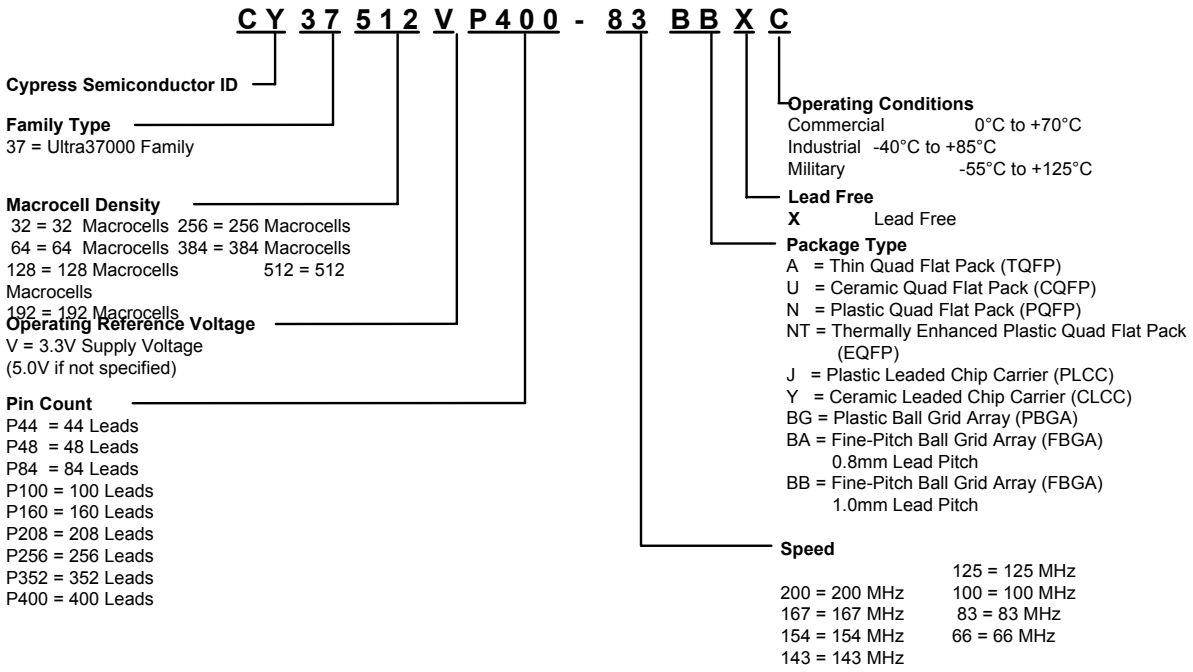


Pin Configurations[20] (continued)

292-Ball PBGA (BG292)
Top View

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	
A	GND	I/O_{21}	NC	I/O_{16}	I/O_{12}	I/O_{9}	I/O_{7}	I/O_{4}	I/O_{0}	I/O_{190}	I/O_{189}	I/O_{186}	I/O_{182}	NC	I/O_{178}	I/O_{175}	NC	NC	I/O_{169}	I/O_{168}	A
B	I/O_{23}	I/O_{20}	I/O_{19}	I/O_{18}	I/O_{15}	I/O_{11}	I/O_{8}	I/O_{5}	I/O_{1}	I/O_{191}	I/O_{187}	I/O_{185}	I/O_{181}	NC	NC	I/O_{174}	I/O_{171}	I/O_{170}	NC	I/O_{166}	B
C	NC	NC	I/O_{22}	NC	I/O_{17}	I/O_{14}	I/O_{10}	I/O_{6}	I/O_{2}	NC	I/O_{188}	I/O_{184}	I/O_{180}	I/O_{179}	I/O_{176}	I/O_{173}	I/O_{172}	I/O_{167}	I/O_{165}	I/O_{162}	C
D	I/O_{24}	NC	NC	GND	NC	V_{CCO}	I/O_{13}	GND	I/O_{3}	NC	V_{CC}	I/O_{183}	GND	I/O_{177}	V_{CCO}	NC	GND	I/O_{164}	TDI	I/O_{160}	D
E	I/O_{27}	I/O_{26}	I/O_{25}	NC													I/O_{163}	I/O_{161}	I/O_{159}	I/O_{156}	E
F	I/O_{30}	TCK	I/O_{28}	V_{CCO}													V_{CCO}	I/O_{158}	NC	I/O_{154}	F
G	I/O_{33}	I/O_{32}	I/O_{31}	I/O_{29}													I/O_{157}	I/O_{155}	I/O_{153}	I/O_{152}	G
H	I/O_{35}	NC	I/O_{34}	GND				GND	GND	GND	GND	GND	GND				GND	I/O_{151}	I/O_{150}	I/O_{149}	H
J	I/O_{39}	I/O_{38}	I/O_{37}	I/O_{36}				GND	GND	GND	GND	GND	GND				I/O_{148}	I/O_{147}	I/O_{146}	I/O_{145}	J
K	I/O_{42}	I/O_{40}	I/O_{41}	V_{CC}				GND	GND	GND	GND	GND	GND				I/O_{144}	CLK_3/I_4	NC	NC	K
L	I/O_{43}	I/O_{44}	I/O_{45}	I/O_{46}				GND	GND	GND	GND	GND	GND				V_{CC}	CLK_2/I_3	I/O_{143}	NC	L
M	I/O_{47}	CLK_0/I_0	CLK_1/I_1	I/O_{48}				GND	GND	GND	GND	GND	GND				I/O_{139}	I/O_{140}	I/O_{141}	I/O_{142}	M
N	I/O_{49}	I/O_{50}	I/O_{51}	GND				GND	GND	GND	GND	GND	GND				GND	I/O_{136}	I/O_{137}	I/O_{138}	N
P	I/O_{52}	I/O_{53}	I/O_{55}	I/O_{58}													I/O_{131}	I/O_{133}	I/O_{134}	I/O_{135}	P
R	I/O_{54}	I/O_{56}	I/O_{59}	V_{CCO}													V_{CCO}	I/O_{130}	NC	I/O_{132}	R
T	I/O_{57}	I/O_{60}	I/O_{62}	I/O_{65}													I/O_{124}	I/O_{127}	I/O_{128}	I/O_{129}	T
U	I/O_{61}	I/O_{63}	I/O_{66}	GND	I/O_{76}	V_{CCO}	I/O_{82}	GND	I/O_{91}	V_{CC}	I/O_{98}	I/O_{102}	GND	I/O_{112}	V_{CCO}	NC	GND	I/O_{123}	I/O_{122}	I/O_{126}	U
V	I/O_{64}	I/O_{67}	I/O_{69}	I/O_{75}	I/O_{78}	I/O_{81}	I/O_{85}	I/O_{88}	I/O_{92}	I_2	I/O_{97}	I/O_{101}	I/O_{105}	I/O_{109}	I/O_{113}	TDO	I/O_{114}	I/O_{117}	I/O_{121}	I/O_{125}	V
W	I/O_{68}	I/O_{70}	I/O_{72}	I/O_{74}	I/O_{79}	I/O_{83}	I/O_{86}	I/O_{89}	I/O_{93}	I/O_{95}	I/O_{96}	I/O_{100}	I/O_{104}	I/O_{107}	I/O_{110}	NC	NC	I/O_{115}	I/O_{118}	I/O_{120}	W
Y	I/O_{71}	I/O_{73}	I/O_{77}	TMS	I/O_{80}	I/O_{84}	I/O_{87}	I/O_{90}	I/O_{94}	NC	NC	I/O_{99}	I/O_{103}	I/O_{106}	I/O_{108}	I/O_{111}	NC	NC	I/O_{116}	I/O_{119}	Y
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	

Ordering Information



5.0V Ordering Information

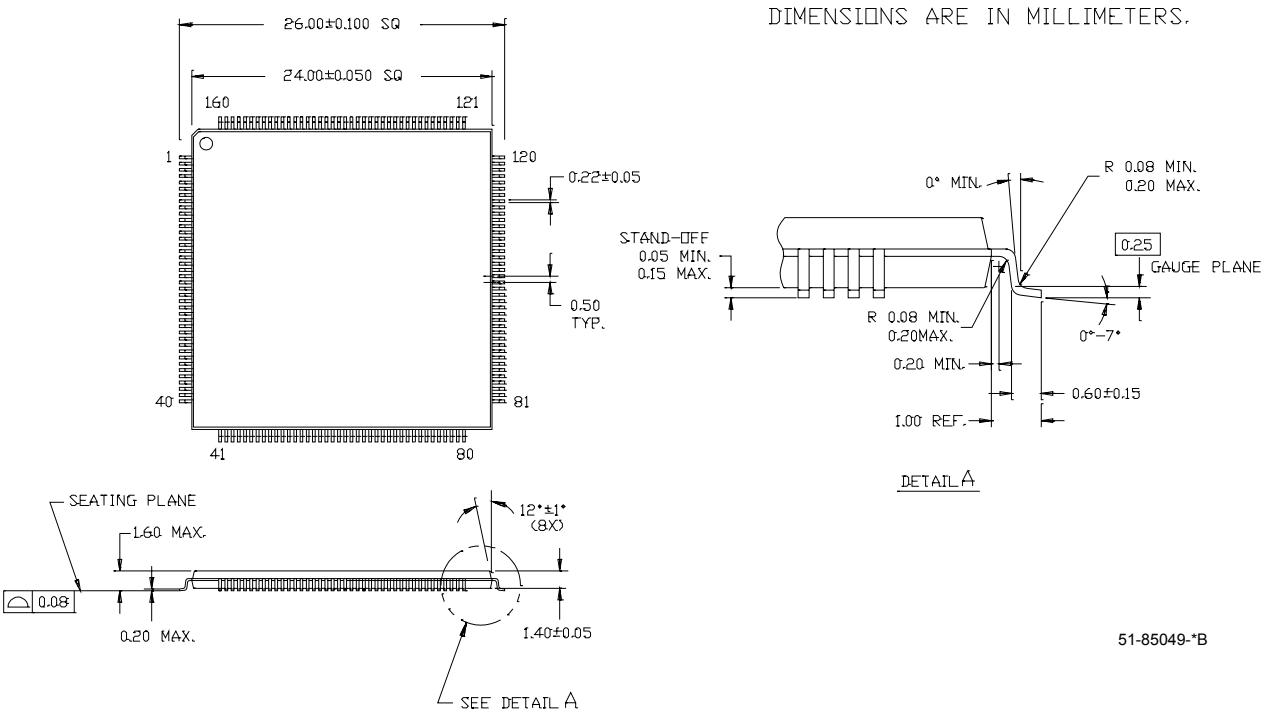
Macrocells	Speed (MHz)	Ordering Code	Package Name	Package Type	Operating Range
32	200	CY37032P44-200AC	A44	44-Lead Thin Quad Flat Pack	Commercial
		CY37032P44-200AXC	A44	44-Lead Lead Free Thin Quad Flat Pack	
		CY37032P44-200JC	J67	44-Lead Plastic Leaded Chip Carrier	
		CY37032P44-200JXC	J67	44-Lead Lead Free Plastic Leaded Chip Carrier	
	154	CY37032P44-154AC	A44	44-Lead Thin Quad Flat Pack	Commercial
		CY37032P44-154JC	J67	44-Lead Plastic Leaded Chip Carrier	
		CY37032P44-154AI	A44	44-Lead Thin Quad Flat Pack	Industrial
		CY37032P44-154AXI	A44	44-Lead Lead Free Thin Quad Flat Pack	
		CY37032P44-154JI	J67	44-Lead Plastic Leaded Chip Carrier	
		CY37032P44-154JXI	J67	44-Lead Lead Free Plastic Leaded Chip Carrier	
	125	CY37032P44-125AC	A44	44-Lead Thin Quad Flat Pack	Commercial
		CY37032P44-125AXC	A44	44-Lead Lead Free Thin Quad Flat Pack	
		CY37032P44-125JC	J67	44-Lead Plastic Leaded Chip Carrier	
		CY37032P44-125JXC	J67	44-Lead Lead Free Plastic Leaded Chip Carrier	
		CY37032P44-125AI	A44	44-Lead Thin Quad Flat Pack	Industrial
		CY37032P44-125JI	J67	44-Lead Plastic Leaded Chip Carrier	
64	200	CY37064P44-200AC	A44	44-Lead Thin Quad Flat Pack	Commercial
		CY37064P44-200AXC	A44	44-Lead Lead Free Thin Quad Flat Pack	
		CY37064P44-200JC	J67	44-Lead Plastic Leaded Chip Carrier	
		CY37064P44-200JXC	J67	44-Lead Lead Free Plastic Leaded Chip Carrier	
		CY37064P84-200JC	J83	84-Lead Plastic Leaded Chip Carrier	
		CY37064P100-200AC	A100	100-Lead Thin Quad Flat Pack	
		CY37064P100-200AXC	A100	100-Lead Lead Free Thin Quad Flat Pack	

5.0V Ordering Information (continued)

Macrocells	Speed (MHz)	Ordering Code	Package Name	Package Type	Operating Range
128	167	CY37128P84-167JC	J83	84-Lead Plastic Leaded Chip Carrier	Commercial
		CY37128P84-167JXC	J83	84-Lead Lead Free Plastic Leaded Chip Carrier	
		CY37128P100-167AC	A100	100-Lead Thin Quad Flat Pack	
		CY37128P100-167AXC	A100	100-Lead Lead Free Thin Quad Flat Pack	
		CY37128P160-167AC	A160	160-Lead Thin Quad Flat Pack	
		CY37128P160-167AXC	A160	160-Lead Lead Free Thin Quad Flat Pack	
	125	CY37128P84-125JC	J83	84-Lead Plastic Leaded Chip Carrier	Commercial
		CY37128P84-125JXC	J83	84-Lead Lead Free Plastic Leaded Chip Carrier	
		CY37128P100-125AC	A100	100-Lead Thin Quad Flat Pack	
		CY37128P100-125AXC	A100	100-Lead Lead Free Thin Quad Flat Pack	
		CY37128P160-125AC	A160	160-Lead Thin Quad Flat Pack	
		CY37128P160-125AXC	A160	160-Lead Lead Free Thin Quad Flat Pack	
		CY37128P84-125JI	J83	84-Lead Plastic Leaded Chip Carrier	Industrial
		CY37128P84-125JXI	J83	84-Lead Lead Free Plastic Leaded Chip Carrier	
		CY37128P100-125AI	A100	100-Lead Thin Quad Flat Pack	
		CY37128P100-125AXI	A100	100-Lead Lead Free Thin Quad Flat Pack	
		CY37128P160-125AI	A160	160-Lead Thin Quad Flat Pack	
		CY37128P160-125AXI	A160	160-Lead Lead Free Thin Quad Flat Pack	
		5962-9952102QYA	Y84	84-Lead Ceramic Leaded Chip Carrier	Military
	100	CY37128P84-100JC	J83	84-Lead Plastic Leaded Chip Carrier	Commercial
		CY37128P84-100JXC	J83	84-Lead Lead Free Plastic Leaded Chip Carrier	
		CY37128P100-100AC	A100	100-Lead Thin Quad Flat Pack	
		CY37128P100-100AXC	A100	100-Lead Lead Free Thin Quad Flat Pack	
		CY37128P160-100AC	A160	160-Lead Thin Quad Flat Pack	
		CY37128P160-100AXC	A160	160-Lead Lead Free Thin Quad Flat Pack	
		CY37128P84-100JI	J83	84-Lead Plastic Leaded Chip Carrier	Industrial
		CY37128P100-100AI	A100	100-Lead Thin Quad Flat Pack	
		CY37128P100-100AXI	A100	100-Lead Lead Free Thin Quad Flat Pack	
		CY37128P160-100AI	A160	160-Lead Thin Quad Flat Pack	
		5962-9952101QYA	Y84	84-Lead Ceramic Leaded Chip Carrier	Military
192	154	CY37192P160-154AC	A160	160-Lead Thin Quad Flat Pack	Commercial
		CY37192P160-154AXC	A160	160-Lead Lead Free Thin Quad Flat Pack	
	125	CY37192P160-125AC	A160	160-Lead Thin Quad Flat Pack	Commercial
		CY37192P160-125AXC	A160	160-Lead Lead Free Thin Quad Flat Pack	
		CY37192P160-125AI	A160	160-Lead Thin Quad Flat Pack	Industrial
		CY37192P160-125AXI	A160	160-Lead Lead Free Thin Quad Flat Pack	
	83	CY37192P160-83AC	A160	160-Lead Thin Quad Flat Pack	Commercial
		CY37192P160-83AXC	A160	160-Lead Lead Free Thin Quad Flat Pack	
		CY37192P160-83AI	A160	160-Lead Thin Quad Flat Pack	Industrial
		CY37192P160-83AXI	A160	160-Lead Lead Free Thin Quad Flat Pack	

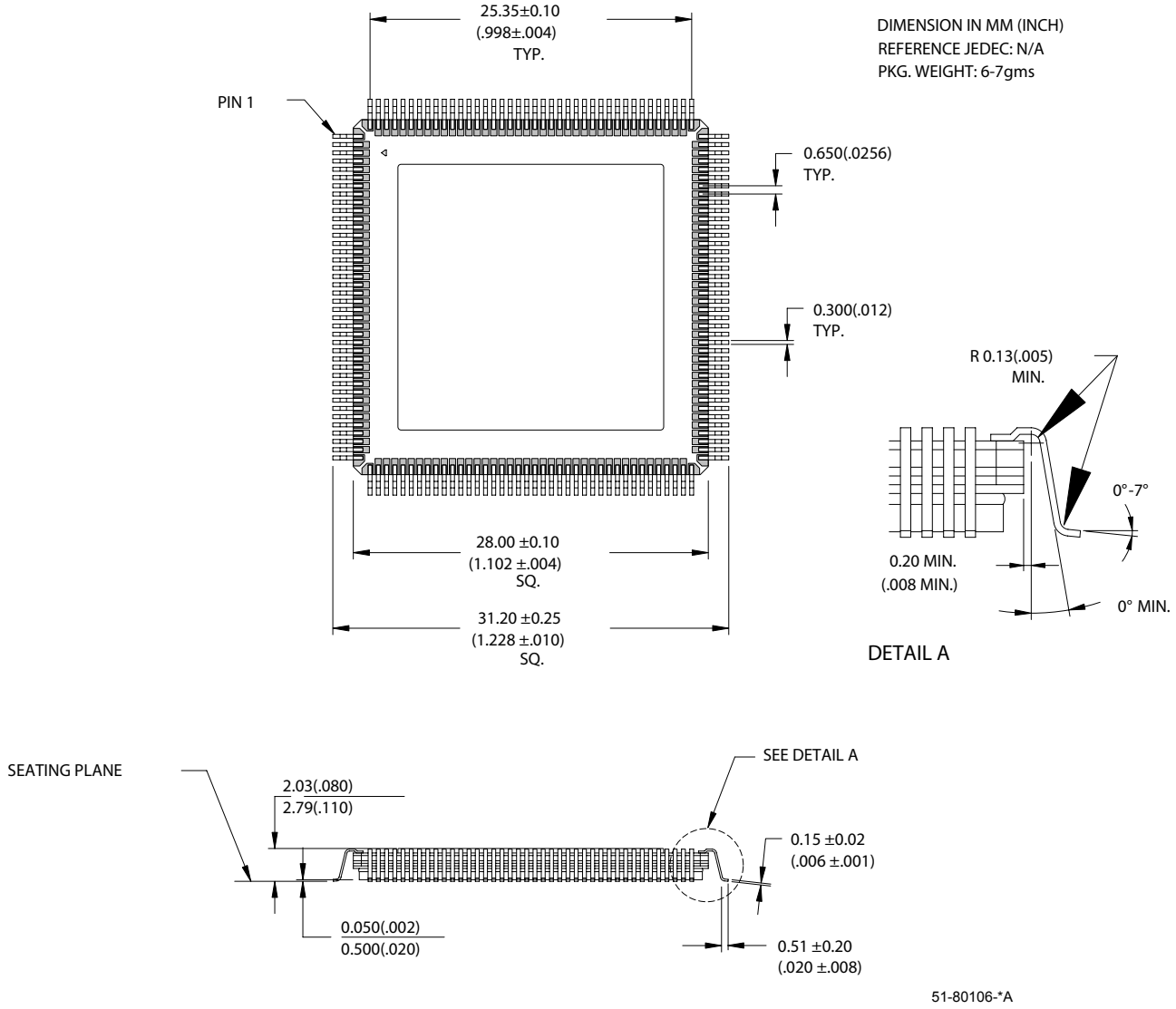
Package Diagrams (continued)

160-Lead Lead (Pb)-Free Thin Plastic Quad Flat Pack (24 x 24 x 1.4 mm) (TQFP) A160



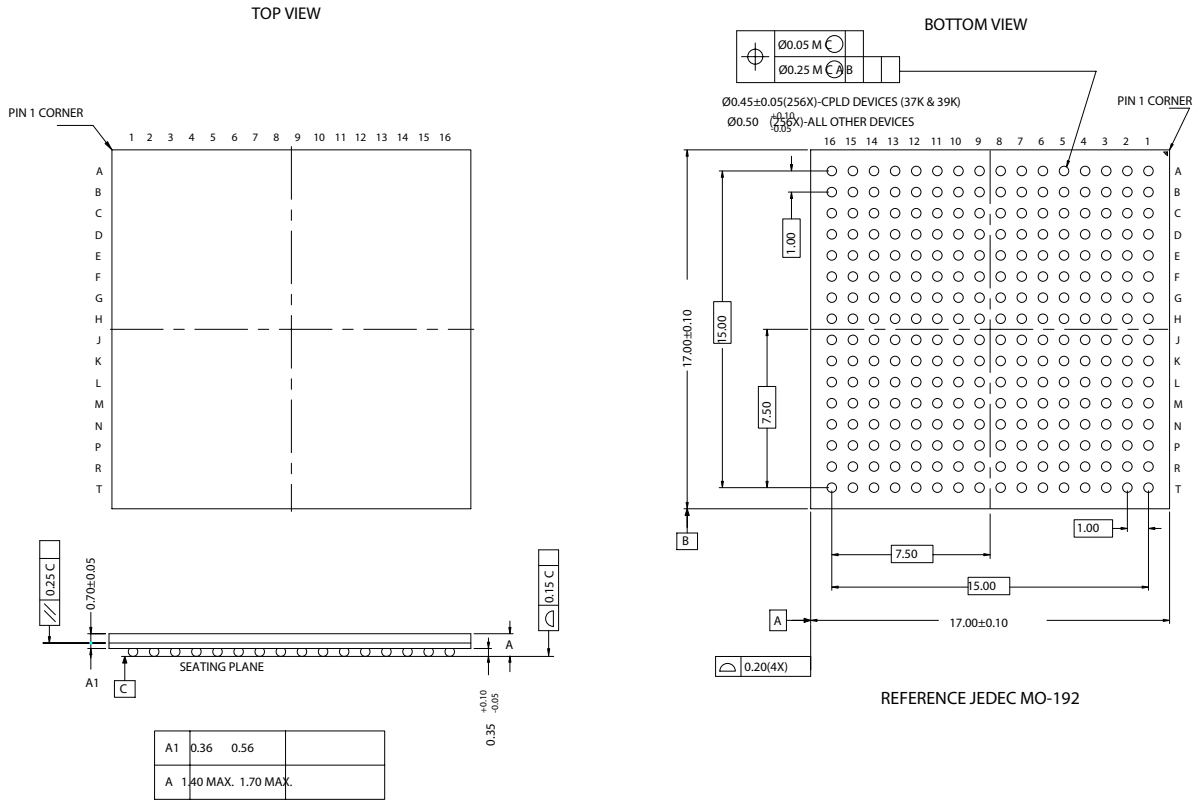
Package Diagrams (continued)

160-Lead Ceramic Quad Flatpack (Cavity Up) U162



Package Diagrams (continued)

256-Ball FBGA (17 x 17 mm) BB256

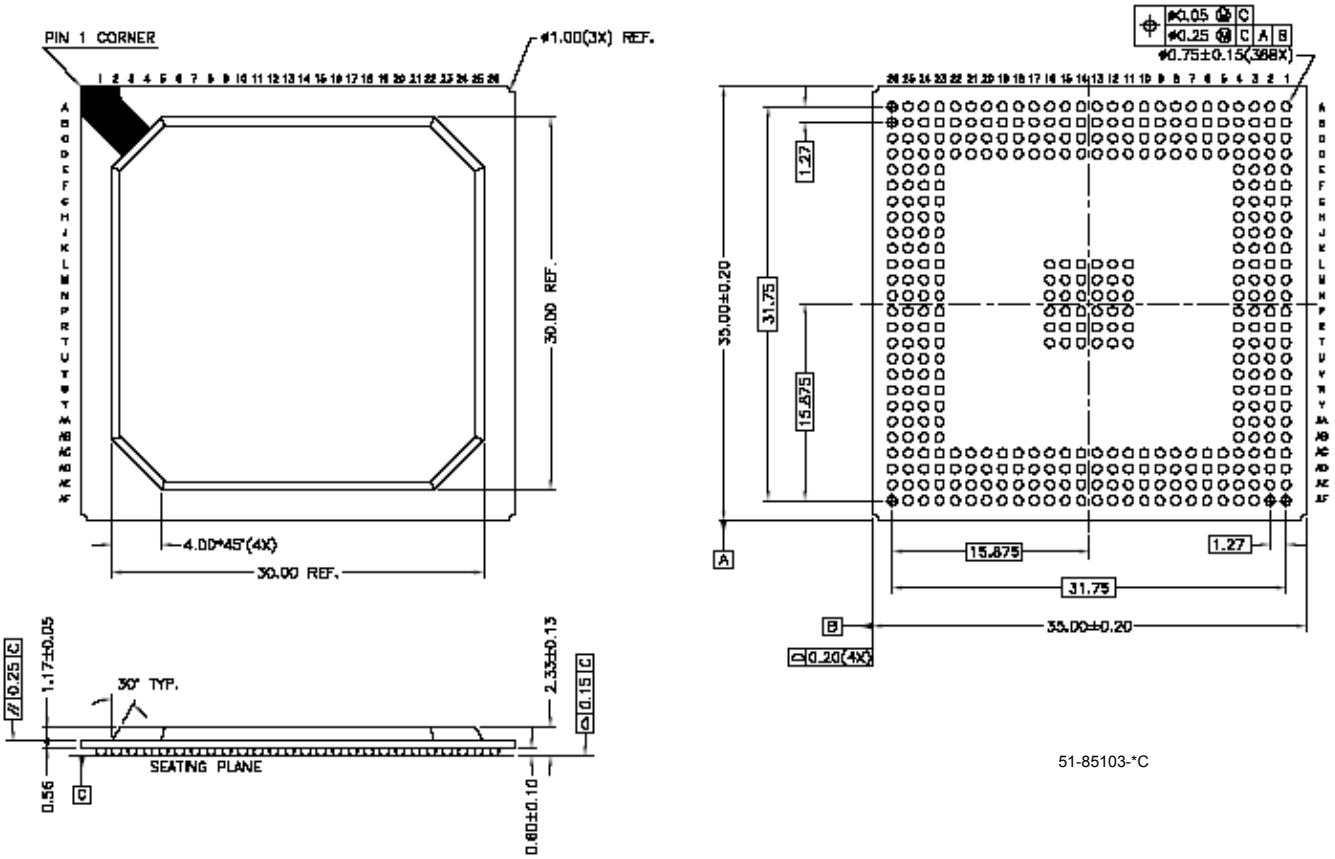


A1	0.36	0.56	
A	1.40 MAX.	1.70 MAX.	

51-85108-*F

Package Diagrams (continued)

388-Ball Plastic Ball Grid Array PBGA (35 x 35 x 2.33 mm) BG388



51-85103-*C

Document History Page

Document Title: Ultra37000 CPLD Family 5V, 3.3V, ISR™ High-Performance CPLDs Document Number: 38-03007				
REV.	**ECN NO.**	**Issue Date**	**Orig. of Change**	**Description of Change**
**	106272	04/18/01	SZV	Change from Spec number: 38-00475 to 38-03007
*A	124942	03/21/03	OOR	Updated 3.3V V_{CC} requirements for –144 speeds Added an Addendum
*B	126262	05/09/03	TEH	Changed pinout for CY37128V BB100 package
*C	128125	07/16/03	HOM	Obsoleted following 3.3V PLCC packaged devices: CY37032VP44-143JC CY37032VP44-100JC CY37032VP44-100JI CY37064VP44-143JC CY37064VP84-143JC CY37064VP44-100JC CY37064VP84-100JC CY37064VP44-100JI CY37064VP84-100JI CY37128VP84-125JC CY37128VP84-83JC CY37128VP84-83JI
*D	282709	See ECN	YDT	Changed package diagrams and labels for consistency Added Lead (Pb)-free logo on first page, as well as a note in Features Added Lead (Pb)-free package diagram labels Added Lead-free Parts to Ordering Information CY37032P44-200AXC, CY37032P44-200JXC, CY37032P44-154AXI, CY37032P44-154JXI, CY37032P44-125AXC, CY37032P44-125JXC, CY37064P44-200AXC, CY37064P44-200JXC, CY37064P100-200AXC, CY37064P44-154AXI, CY37064P44-154JXI, CY37064P44-125AXC, CY37064P44-125JXC, CY37064P100-125AXC, CY37064P44-125AXI, CY37064P100-125AXI, CY37128P84-167JXC, CY37128P100-167AXC, CY37128P160-167AXC, CY37128P84-125JXC, CY37128P100-125AXC, CY37128P160-125AXC, CY37128P84-125JXI, CY37128P100-125AXI, CY37128P160-125AXI, CY37128P84-100JXC, CY37128P100-100AXC, CY37128P160-100AXC, CY37128P100-100AXI, CY37192P160-154AXC, CY37192P160-125AXC, CY37192P160-125AXI, CY37192P160-83AXC, CY37192P160-83AXI, CY37256P160-154AXC, CY37256P160-125AXC, CY37256P160-125AXI, CY37256P160-83AXC, CY37256P160-83AXI, CY37032VP44-143AXC, CY37032VP44-100AXC, CY37032VP44-100AXI, CY37032VP44-100JXI, CY37064VP44-143AXC, CY37064VP100-143AXC, CY37064VP44-100AXC, CY37064VP100-100AXC, CY37064VP44-100AXI, CY37064VP100-100AXI, CY37128VP100-125AXC, CY37128VP160-125AXC, CY37128VP160-125AXI, CY37128VP100-83AXC, CY37128VP160-83AXC, CY37128VP100-83AXI, CY37128VP160-83AXI, CY37192VP160-100AXC, CY37192VP160-66AXC, CY37256VP160-100AXC, CY37256VP160-100AXI, CY37256VP160-66AXC
*E	321635	See ECN	PCX	Added Package Diagram BG292 Updated all PBGA package type information (BG292 & BG388)